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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

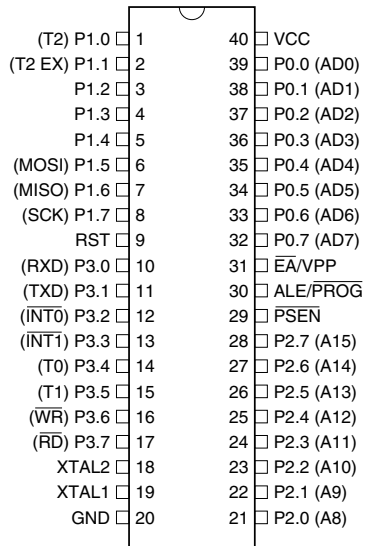
Applications of "[Embedded - Microcontrollers](#)"

Details

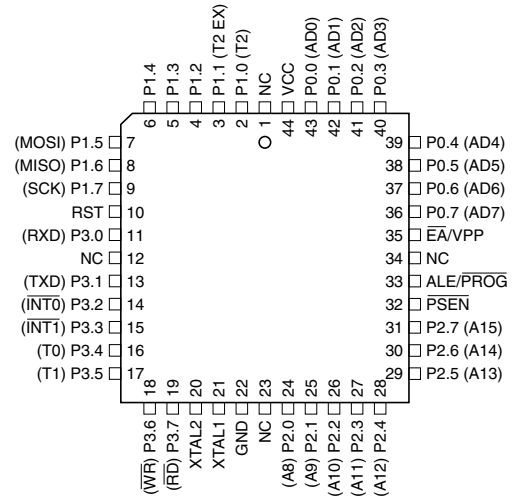
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	24MHz
Connectivity	UART/USART
Peripherals	WDT
Number of I/O	32
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89s52-24ai

2. Pin Configurations

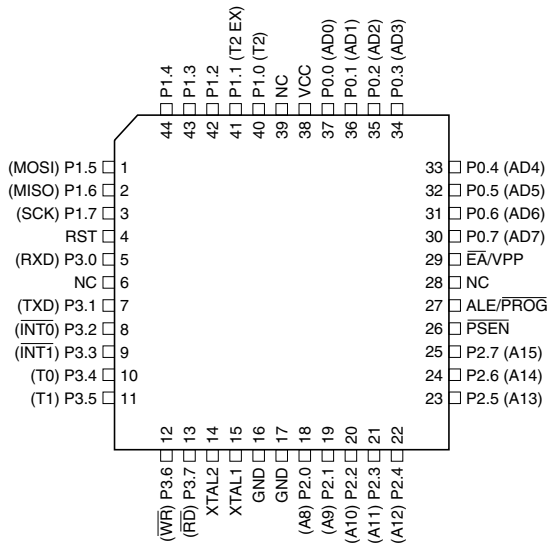
2.1 40-lead PDIP



2.3 44-lead PLCC



2.2 44-lead TQFP



4. Pin Description

4.1 VCC

Supply voltage.

4.2 GND

Ground.

4.3 Port 0

Port 0 is an 8-bit open drain bidirectional I/O port. As an output port, each pin can sink eight TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 can also be configured to be the multiplexed low-order address/data bus during accesses to external program and data memory. In this mode, P0 has internal pull-ups.

Port 0 also receives the code bytes during Flash programming and outputs the code bytes during program verification. **External pull-ups are required during program verification.**

4.4 Port 1

Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. The Port 1 output buffers can sink/source four TTL inputs. When 1s are written to Port 1 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (I_{IL}) because of the internal pull-ups.

In addition, P1.0 and P1.1 can be configured to be the timer/counter 2 external count input (P1.0/T2) and the timer/counter 2 trigger input (P1.1/T2EX), respectively, as shown in the following table.

Port 1 also receives the low-order address bytes during Flash programming and verification.

Port Pin	Alternate Functions
P1.0	T2 (external count input to Timer/Counter 2), clock-out
P1.1	T2EX (Timer/Counter 2 capture/reload trigger and direction control)
P1.5	MOSI (used for In-System Programming)
P1.6	MISO (used for In-System Programming)
P1.7	SCK (used for In-System Programming)

4.5 Port 2

Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. The Port 2 output buffers can sink/source four TTL inputs. When 1s are written to Port 2 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current (I_{IL}) because of the internal pull-ups.

Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application, Port 2 uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during Flash programming and verification.

4.6 Port 3

Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pull-ups.

Port 3 receives some control signals for Flash programming and verification.

Port 3 also serves the functions of various special features of the AT89S52, as shown in the following table.

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	$\overline{INT0}$ (external interrupt 0)
P3.3	$\overline{INT1}$ (external interrupt 1)
P3.4	T0 (timer 0 external input)
P3.5	T1 (timer 1 external input)
P3.6	\overline{WR} (external data memory write strobe)
P3.7	\overline{RD} (external data memory read strobe)

4.7 RST

Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device. This pin drives high for 98 oscillator periods after the Watchdog times out. The DISRTO bit in SFR AUXR (address 8EH) can be used to disable this feature. In the default state of bit DISRTO, the RESET HIGH out feature is enabled.

4.8 ALE/ \overline{PROG}

Address Latch Enable (ALE) is an output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input (\overline{PROG}) during Flash programming.

In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external data memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.

6. Memory Organization

MCS-51 devices have a separate address space for Program and Data Memory. Up to 64K bytes each of external Program and Data Memory can be addressed.

6.1 Program Memory

If the \overline{EA} pin is connected to GND, all program fetches are directed to external memory.

On the AT89S52, if \overline{EA} is connected to V_{CC} , program fetches to addresses 0000H through 1FFFH are directed to internal memory and fetches to addresses 2000H through FFFFH are to external memory.

6.2 Data Memory

The AT89S52 implements 256 bytes of on-chip RAM. The upper 128 bytes occupy a parallel address space to the Special Function Registers. This means that the upper 128 bytes have the same addresses as the SFR space but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the address mode used in the instruction specifies whether the CPU accesses the upper 128 bytes of RAM or the SFR space. Instructions which use direct addressing access the SFR space.

For example, the following direct addressing instruction accesses the SFR at location 0A0H (which is P2).

```
MOV 0A0H, #data
```

Instructions that use indirect addressing access the upper 128 bytes of RAM. For example, the following indirect addressing instruction, where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

```
MOV @R0, #data
```

Note that stack operations are examples of indirect addressing, so the upper 128 bytes of data RAM are available as stack space.

7. Watchdog Timer (One-time Enabled with Reset-out)

The WDT is intended as a recovery method in situations where the CPU may be subjected to software upsets. The WDT consists of a 14-bit counter and the Watchdog Timer Reset (WDTRST) SFR. The WDT is defaulted to disable from exiting reset. To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, it will increment every machine cycle while the oscillator is running. The WDT timeout period is dependent on the external clock frequency. There is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When WDT overflows, it will drive an output RESET HIGH pulse at the RST pin.

7.1 Using the WDT

To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, the user needs to service it by writing 01EH and 0E1H to WDTRST to avoid a WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH), and this will reset the device. When the WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycles. To reset the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write-only register. The WDT counter cannot be read or written. When

10. Timer 2

Timer 2 is a 16-bit Timer/Counter that can operate as either a timer or an event counter. The type of operation is selected by bit $C/\overline{T}2$ in the SFR T2CON (shown in Table 5-2). Timer 2 has three operating modes: capture, auto-reload (up or down counting), and baud rate generator. The modes are selected by bits in T2CON, as shown in Table 10-1. Timer 2 consists of two 8-bit registers, TH2 and TL2. In the Timer function, the TL2 register is incremented every machine cycle. Since a machine cycle consists of 12 oscillator periods, the count rate is 1/12 of the oscillator frequency.

Table 10-1. Timer 2 Operating Modes

RCLK +TCLK	CP/ $\overline{RL}2$	TR2	MODE
0	0	1	16-bit Auto-reload
0	1	1	16-bit Capture
1	X	1	Baud Rate Generator
X	X	0	(Off)

In the Counter function, the register is incremented in response to a 1-to-0 transition at its corresponding external input pin, T2. In this function, the external input is sampled during S5P2 of every machine cycle. When the samples show a high in one cycle and a low in the next cycle, the count is incremented. The new count value appears in the register during S3P1 of the cycle following the one in which the transition was detected. Since two machine cycles (24 oscillator periods) are required to recognize a 1-to-0 transition, the maximum count rate is 1/24 of the oscillator frequency. To ensure that a given level is sampled at least once before it changes, the level should be held for at least one full machine cycle.

10.1 Capture Mode

In the capture mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 is a 16-bit timer or counter which upon overflow sets bit TF2 in T2CON. This bit can then be used to generate an interrupt. If EXEN2 = 1, Timer 2 performs the same operation, but a 1-to-0 transition at external input T2EX also causes the current value in TH2 and TL2 to be captured into RCAP2H and RCAP2L, respectively. In addition, the transition at T2EX causes bit EXF2 in T2CON to be set. The EXF2 bit, like TF2, can generate an interrupt. The capture mode is illustrated in Figure 10-1.

10.2 Auto-reload (Up or Down Counter)

Timer 2 can be programmed to count up or down when configured in its 16-bit auto-reload mode. This feature is invoked by the DCEN (Down Counter Enable) bit located in the SFR T2MOD (see Table 10-2). Upon reset, the DCEN bit is set to 0 so that timer 2 will default to count up. When DCEN is set, Timer 2 can count up or down, depending on the value of the T2EX pin.

Figure 10-2. Timer 2 Auto Reload Mode (DCEN = 0)

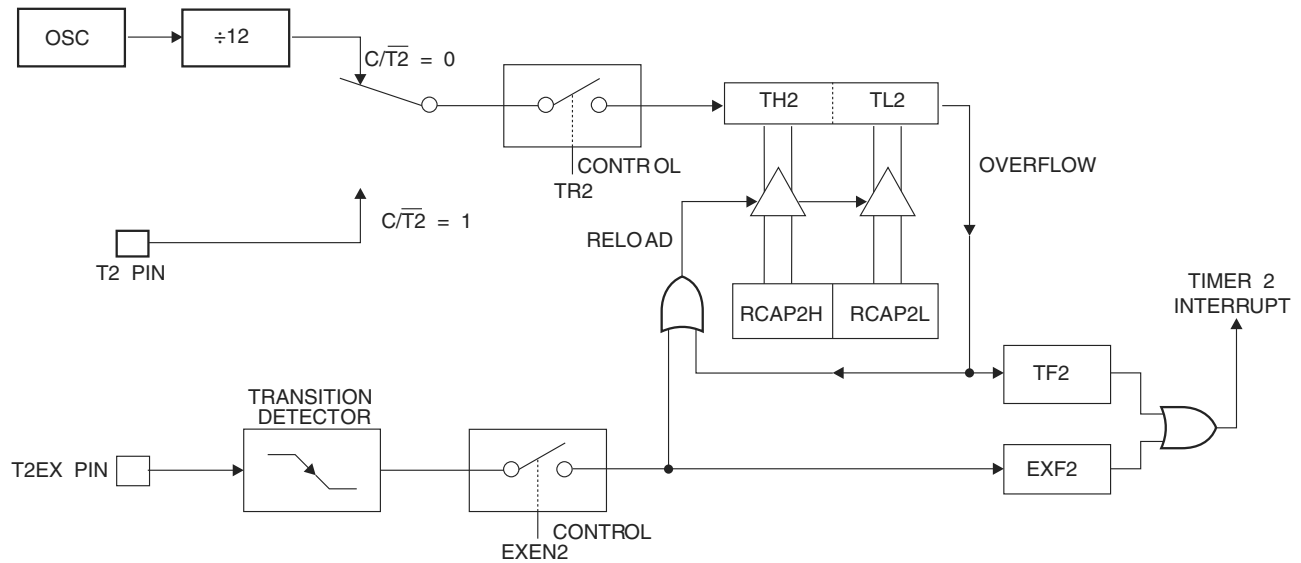


Figure 10-3. Timer 2 Auto Reload Mode (DCEN = 1)

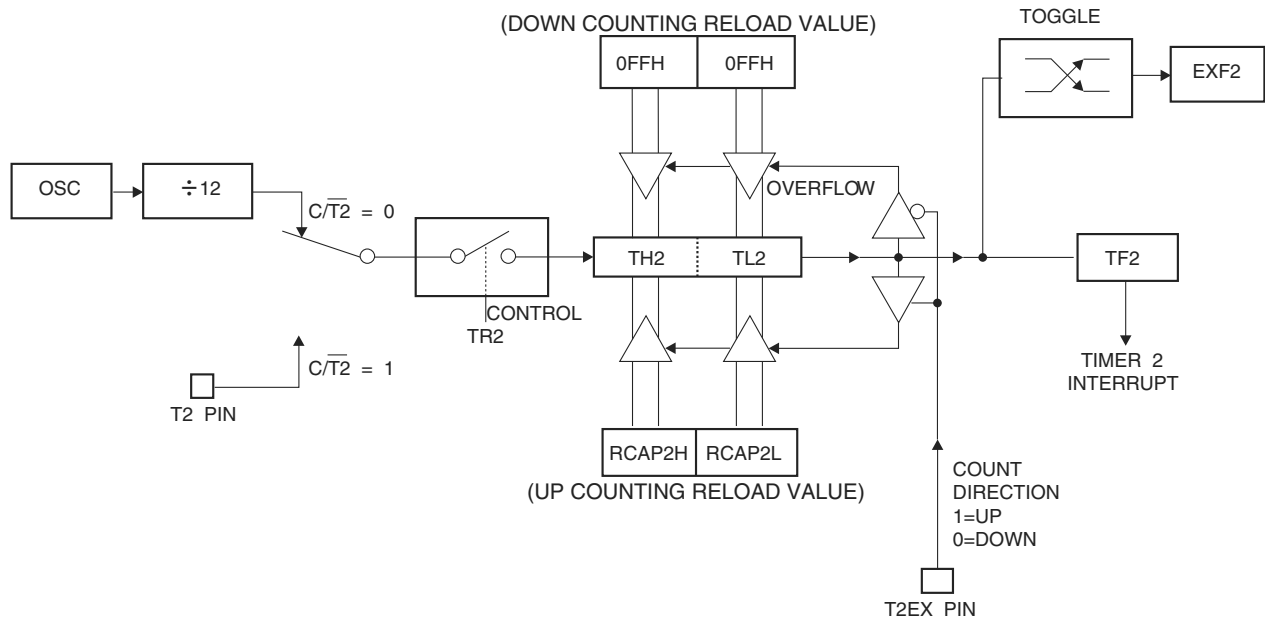
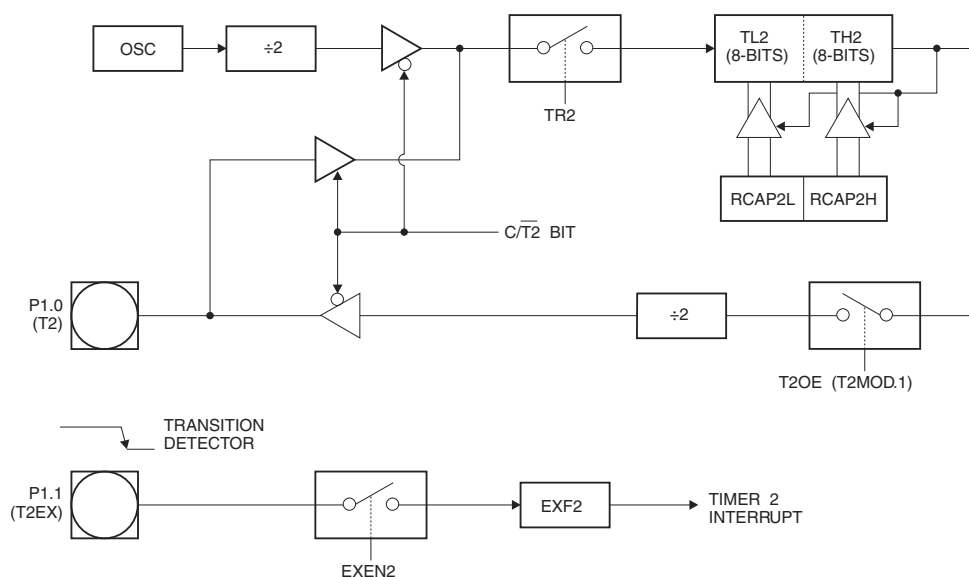


Figure 12-1. Timer 2 in Clock-Out Mode


13. Interrupts

The AT89S52 has a total of six interrupt vectors: two external interrupts ($\overline{\text{INT0}}$ and $\overline{\text{INT1}}$), three timer interrupts (Timers 0, 1, and 2), and the serial port interrupt. These interrupts are all shown in Figure 13-1.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE. IE also contains a global disable bit, EA, which disables all interrupts at once.

Note that Table 13-1 shows that bit position IE.6 is unimplemented. User software should not write a 1 to this bit position, since it may be used in future AT89 products.

Timer 2 interrupt is generated by the logical OR of bits TF2 and EXF2 in register T2CON. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine may have to determine whether it was TF2 or EXF2 that generated the interrupt, and that bit will have to be cleared in software.

The Timer 0 and Timer 1 flags, TF0 and TF1, are set at S5P2 of the cycle in which the timers overflow. The values are then polled by the circuitry in the next cycle. However, the Timer 2 flag, TF2, is set at S2P2 and is polled in the same cycle in which the timer overflows.

14. Oscillator Characteristics

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier that can be configured for use as an on-chip oscillator, as shown in Figure 16-1. Either a quartz crystal or ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven, as shown in Figure 16-2. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

15. Idle Mode

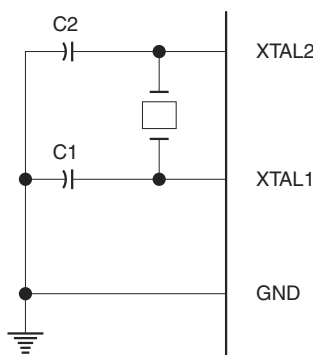
In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the special functions registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

Note that when idle mode is terminated by a hardware reset, the device normally resumes program execution from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when idle mode is terminated by a reset, the instruction following the one that invokes idle mode should not write to a port pin or to external memory.

16. Power-down Mode

In the Power-down mode, the oscillator is stopped, and the instruction that invokes Power-down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power-down mode is terminated. Exit from Power-down mode can be initiated either by a hardware reset or by an enabled external interrupt. Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before V_{CC} is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

Figure 16-1. Oscillator Connections



Note: 1. $C1, C2 = 30 \text{ pF} \pm 10 \text{ pF}$ for Crystals
 $= 40 \text{ pF} \pm 10 \text{ pF}$ for Ceramic Resonators

Figure 16-2. External Clock Drive Configuration

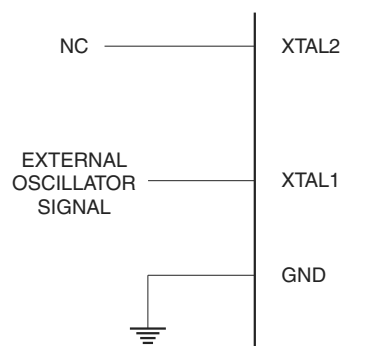


Table 16-1. Status of External Pins During Idle and Power-down Modes

Mode	Program Memory	ALE	$\overline{\text{PSEN}}$	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

17. Program Memory Lock Bits

The AT89S52 has three lock bits that can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in Table 17-1.

Table 17-1. Lock Bit Protection Modes

Program Lock Bits				Protection Type
	LB1	LB2	LB3	
1	U	U	U	No program lock features
2	P	U	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{\text{EA}}$ is sampled and latched on reset, and further programming of the Flash memory is disabled
3	P	P	U	Same as mode 2, but verify is also disabled
4	P	P	P	Same as mode 3, but external execution is also disabled

When lock bit 1 is programmed, the logic level at the $\overline{\text{EA}}$ pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value and holds that value until reset is activated. The latched value of $\overline{\text{EA}}$ must agree with the current logic level at that pin in order for the device to function properly.

18. Programming the Flash – Parallel Mode

The AT89S52 is shipped with the on-chip Flash memory array ready to be programmed. The programming interface needs a high-voltage (12-volt) program enable signal and is compatible with conventional third-party Flash or EPROM programmers.

The AT89S52 code memory array is programmed byte-by-byte.

Programming Algorithm: Before programming the AT89S52, the address, data, and control signals should be set up according to the “Flash Programming Modes” (Table 22-1) and Figure 22-1 and Figure 22-2. To program the AT89S52, take the following steps:

1. Input the desired memory location on the address lines.
2. Input the appropriate data byte on the data lines.
3. Activate the correct combination of control signals.
4. Raise \overline{EA}/V_{PP} to 12V.
5. Pulse ALE/\overline{PROG} once to program a byte in the Flash array or the lock bits. The byte-write cycle is self-timed and typically takes no more than 50 μs . Repeat steps 1 through 5, changing the address and data for the entire array or until the end of the object file is reached.

Data Polling: The AT89S52 features \overline{Data} Polling to indicate the end of a byte write cycle. During a write cycle, an attempted read of the last byte written will result in the complement of the written data on P0.7. Once the write cycle has been completed, true data is valid on all outputs, and the next cycle may begin. \overline{Data} Polling may begin any time after a write cycle has been initiated.

Ready/ \overline{Busy} : The progress of byte programming can also be monitored by the RDY/\overline{BSY} output signal. P3.0 is pulled low after ALE goes high during programming to indicate \overline{BUSY} . P3.0 is pulled high again when programming is done to indicate $READY$.

Program Verify: If lock bits LB1 and LB2 have not been programmed, the programmed code data can be read back via the address and data lines for verification. **The status of the individual lock bits can be verified directly by reading them back.**

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 000H, 100H, and 200H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows.

(000H) = 1EH indicates manufactured by Atmel
 (100H) = 52H indicates AT89S52
 (200H) = 06H

Chip Erase: In the parallel programming mode, a chip erase operation is initiated by using the proper combination of control signals and by pulsing ALE/\overline{PROG} low for a duration of 200 ns - 500 ns.

In the serial programming mode, a chip erase operation is initiated by issuing the Chip Erase instruction. In this mode, chip erase is self-timed and takes about 500 ms.






During chip erase, a serial read from any address location will return 00H at the data output.

22. Programming Interface – Parallel Mode

Every code byte in the Flash array can be programmed by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

Most major worldwide programming vendors offer support for the Atmel AT89 microcontroller series. Please contact your local programming vendor for the appropriate software revision.

Table 22-1. Flash Programming Modes

Mode	V _{CC}	RST	$\overline{\text{PSEN}}$	$\overline{\text{ALE/PROG}}$	$\overline{\text{EA/V}}_{\text{PP}}$	P2.6	P2.7	P3.3	P3.6	P3.7	P0.7-0 Data	P2.4-0	P1.7-0
												Address	
Write Code Data	5V	H	L		12V	L	H	H	H	H	D _{IN}	A12-8	A7-0
Read Code Data	5V	H	L	H	H	L	L	L	H	H	D _{OUT}	A12-8	A7-0
Write Lock Bit 1	5V	H	L		12V	H	H	H	H	H	X	X	X
Write Lock Bit 2	5V	H	L		12V	H	H	H	L	L	X	X	X
Write Lock Bit 3	5V	H	L		12V	H	L	H	H	L	X	X	X
Read Lock Bits 1, 2, 3	5V	H	L	H	H	H	H	L	H	L	P0.2, P0.3, P0.4	X	X
Chip Erase	5V	H	L		12V	H	L	H	L	L	X	X	X
Read Atmel ID	5V	H	L	H	H	L	L	L	L	L	1EH	X 0000	00H
Read Device ID	5V	H	L	H	H	L	L	L	L	L	52H	X 0001	00H
Read Device ID	5V	H	L	H	H	L	L	L	L	L	06H	X 0010	00H

- Notes:
1. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Chip Erase.
 2. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Write Code Data.
 3. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Write Lock Bits.
 4. RDY/BSY signal is output on P3.0 during programming.
 5. X = don't care.

23. Flash Programming and Verification Characteristics (Parallel Mode)

$T_A = 20^\circ\text{C}$ to 30°C , $V_{CC} = 4.5$ to 5.5V

Symbol	Parameter	Min	Max	Units
V_{PP}	Programming Supply Voltage	11.5	12.5	V
I_{PP}	Programming Supply Current		10	mA
I_{CC}	V_{CC} Supply Current		30	mA
$1/t_{CLCL}$	Oscillator Frequency	3	33	MHz
t_{AVGL}	Address Setup to \overline{PROG} Low	$48 t_{CLCL}$		
t_{GHAX}	Address Hold After \overline{PROG}	$48 t_{CLCL}$		
t_{DVGL}	Data Setup to \overline{PROG} Low	$48 t_{CLCL}$		
t_{GHDX}	Data Hold After \overline{PROG}	$48 t_{CLCL}$		
t_{EHS}	P2.7 (\overline{ENABLE}) High to V_{PP}	$48 t_{CLCL}$		
t_{SHGL}	V_{PP} Setup to \overline{PROG} Low	10		μs
t_{GHSL}	V_{PP} Hold After \overline{PROG}	10		μs
t_{GLGH}	\overline{PROG} Width	0.2	1	μs
t_{AVQV}	Address to Data Valid		$48 t_{CLCL}$	
t_{ELQV}	\overline{ENABLE} Low to Data Valid		$48 t_{CLCL}$	
t_{EHQZ}	Data Float After \overline{ENABLE}	0	$48 t_{CLCL}$	
t_{GHBL}	\overline{PROG} High to \overline{BUSY} Low		1.0	μs
t_{WC}	Byte Write Cycle Time		50	μs

Figure 23-1. Flash Programming and Verification Waveforms – Parallel Mode

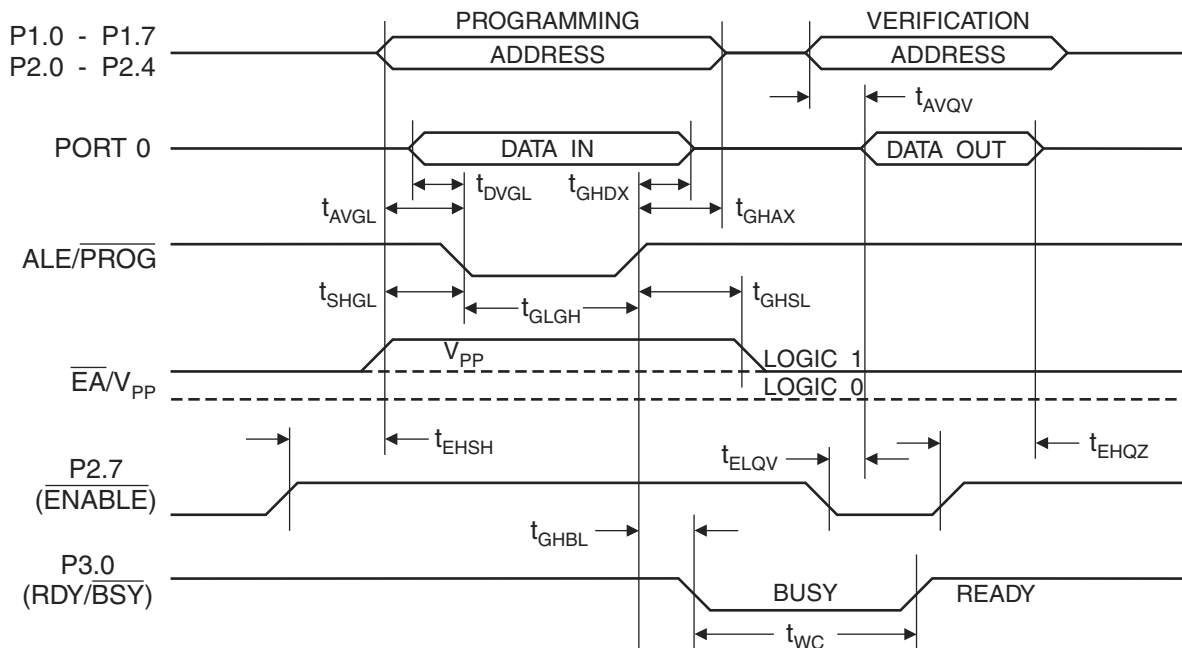
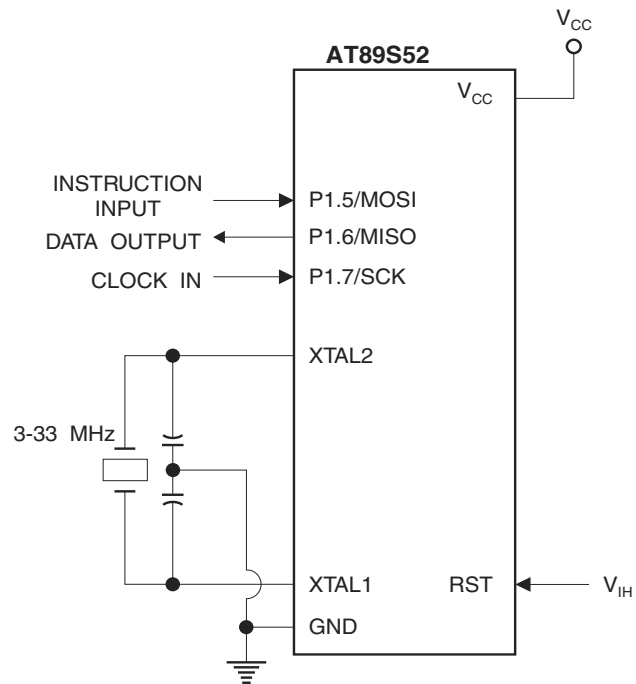
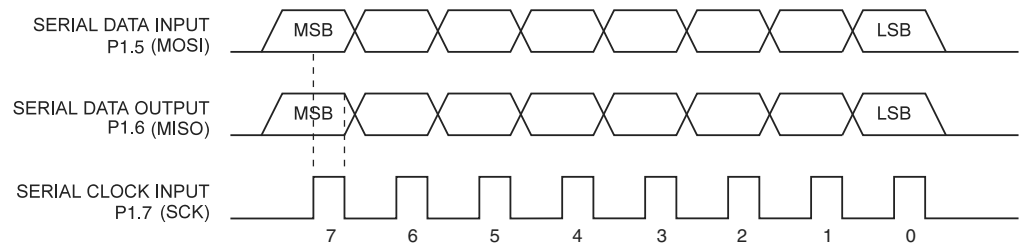


Figure 23-2. Flash Memory Serial Downloading



24. Flash Programming and Verification Waveforms – Serial Mode

Figure 24-1. Serial Programming Waveforms



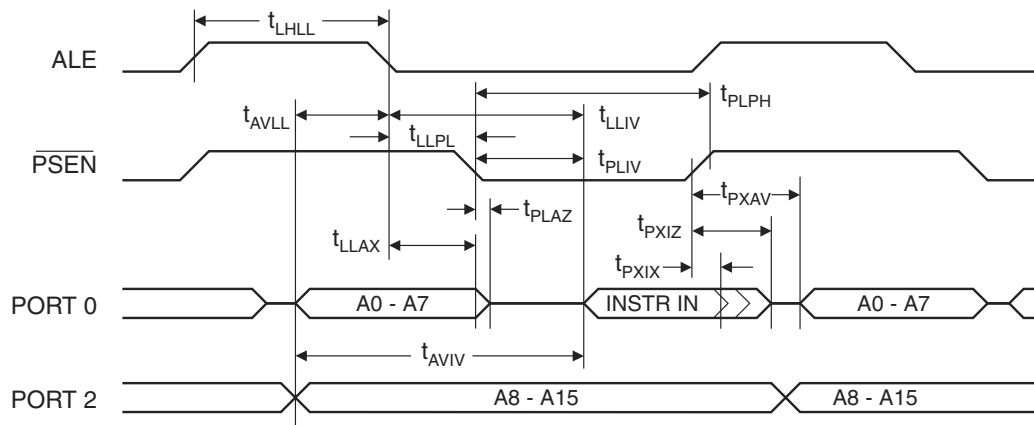
28. AC Characteristics

Under operating conditions, load capacitance for Port 0, ALE/ $\overline{\text{PROG}}$, and $\overline{\text{PSEN}}$ = 100 pF; load capacitance for all other outputs = 80 pF.

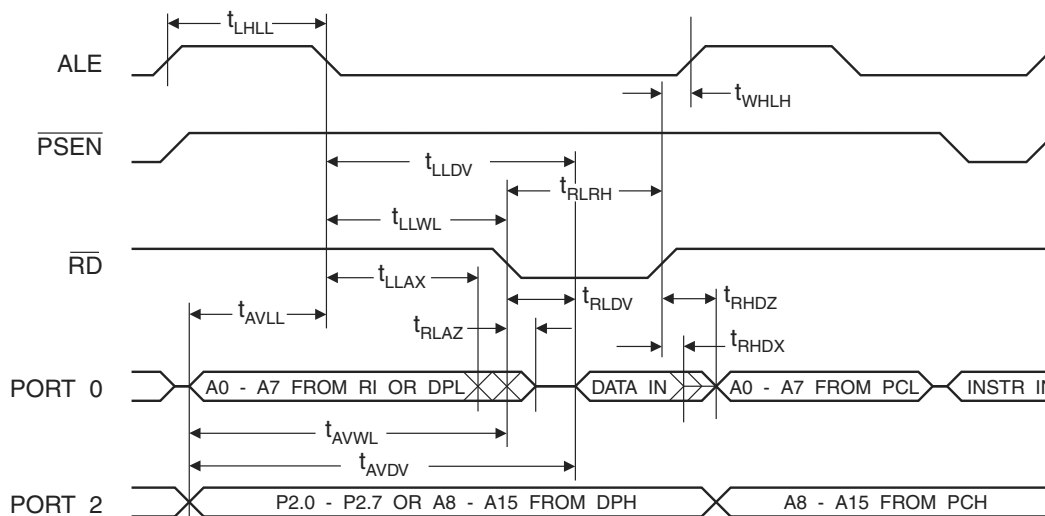
28.1 External Program and Data Memory Characteristics

Symbol	Parameter	12 MHz Oscillator		Variable Oscillator		Units
		Min	Max	Min	Max	
$1/t_{\text{CLCL}}$	Oscillator Frequency			0	33	MHz
t_{LHLL}	ALE Pulse Width	127		$2t_{\text{CLCL}}-40$		ns
t_{AVLL}	Address Valid to ALE Low	43		$t_{\text{CLCL}}-25$		ns
t_{LLAX}	Address Hold After ALE Low	48		$t_{\text{CLCL}}-25$		ns
t_{LLIV}	ALE Low to Valid Instruction In		233		$4t_{\text{CLCL}}-65$	ns
t_{LLPL}	ALE Low to $\overline{\text{PSEN}}$ Low	43		$t_{\text{CLCL}}-25$		ns
t_{PLPH}	$\overline{\text{PSEN}}$ Pulse Width	205		$3t_{\text{CLCL}}-45$		ns
t_{PLIV}	$\overline{\text{PSEN}}$ Low to Valid Instruction In		145		$3t_{\text{CLCL}}-60$	ns
t_{PXIX}	Input Instruction Hold After $\overline{\text{PSEN}}$	0		0		ns
t_{PXIZ}	Input Instruction Float After $\overline{\text{PSEN}}$		59		$t_{\text{CLCL}}-25$	ns
t_{PXAV}	$\overline{\text{PSEN}}$ to Address Valid	75		$t_{\text{CLCL}}-8$		ns
t_{AVIV}	Address to Valid Instruction In		312		$5t_{\text{CLCL}}-80$	ns
t_{PLAZ}	$\overline{\text{PSEN}}$ Low to Address Float		10		10	ns
t_{RLRH}	$\overline{\text{RD}}$ Pulse Width	400		$6t_{\text{CLCL}}-100$		ns
t_{WLWH}	$\overline{\text{WR}}$ Pulse Width	400		$6t_{\text{CLCL}}-100$		ns
t_{RLDV}	$\overline{\text{RD}}$ Low to Valid Data In		252		$5t_{\text{CLCL}}-90$	ns
t_{RHDX}	Data Hold After $\overline{\text{RD}}$	0		0		ns
t_{RHDZ}	Data Float After $\overline{\text{RD}}$		97		$2t_{\text{CLCL}}-28$	ns
t_{LLDV}	ALE Low to Valid Data In		517		$8t_{\text{CLCL}}-150$	ns
t_{AVDV}	Address to Valid Data In		585		$9t_{\text{CLCL}}-165$	ns
t_{LLWL}	ALE Low to $\overline{\text{RD}}$ or $\overline{\text{WR}}$ Low	200	300	$3t_{\text{CLCL}}-50$	$3t_{\text{CLCL}}+50$	ns
t_{AVWL}	Address to $\overline{\text{RD}}$ or $\overline{\text{WR}}$ Low	203		$4t_{\text{CLCL}}-75$		ns
t_{QVWX}	Data Valid to $\overline{\text{WR}}$ Transition	23		$t_{\text{CLCL}}-30$		ns
t_{QVWH}	Data Valid to $\overline{\text{WR}}$ High	433		$7t_{\text{CLCL}}-130$		ns
t_{WHQX}	Data Hold After $\overline{\text{WR}}$	33		$t_{\text{CLCL}}-25$		ns
t_{RLAZ}	$\overline{\text{RD}}$ Low to Address Float		0		0	ns
t_{WHLH}	$\overline{\text{RD}}$ or $\overline{\text{WR}}$ High to ALE High	43	123	$t_{\text{CLCL}}-25$	$t_{\text{CLCL}}+25$	ns

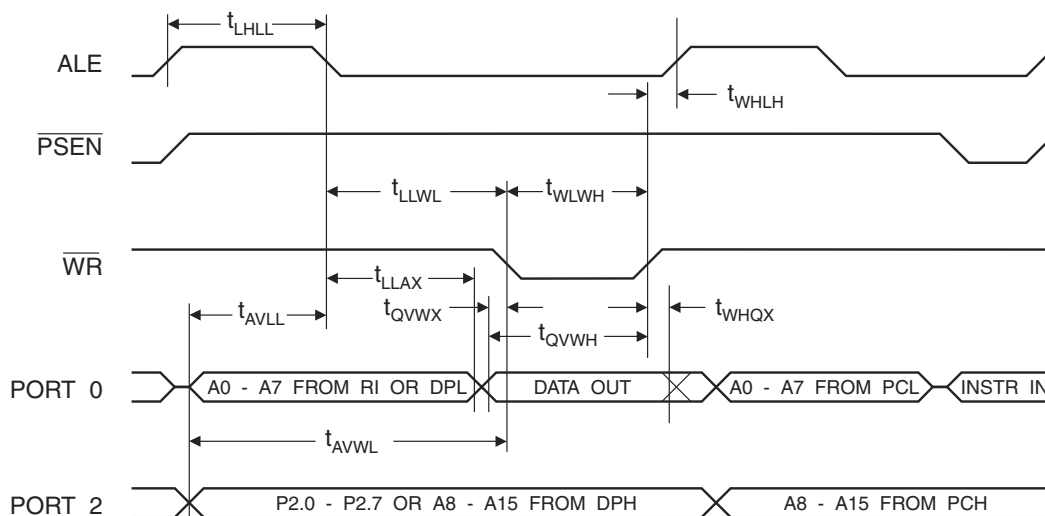
29. External Program Memory Read Cycle



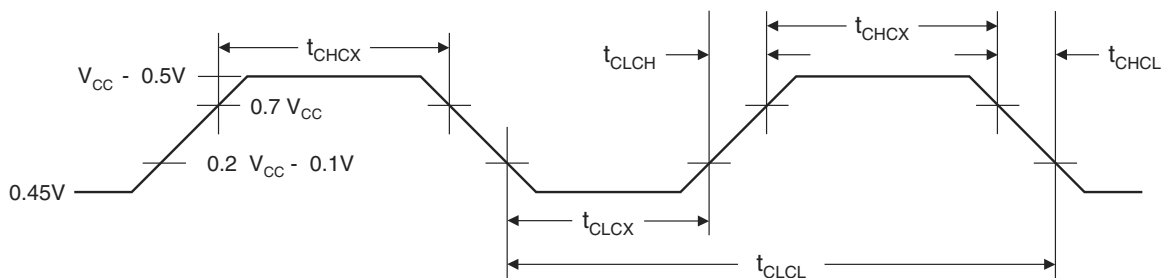
30. External Data Memory Read Cycle



31. External Data Memory Write Cycle



32. External Clock Drive Waveforms

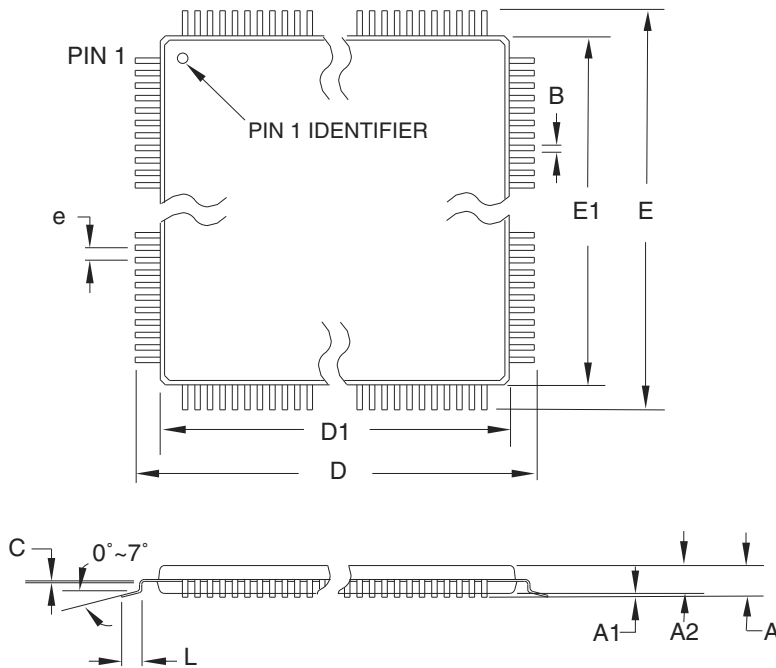


33. External Clock Drive

Symbol	Parameter	Min	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	0	33	MHz
t_{CLCL}	Clock Period	30		ns
t_{CHCX}	High Time	12		ns
t_{CLCX}	Low Time	12		ns
t_{CLCH}	Rise Time		5	ns
t_{CHCL}	Fall Time		5	ns

39. Packaging Information

39.1 44A – TQFP



COMMON DIMENSIONS
(Unit of Measure = mm)

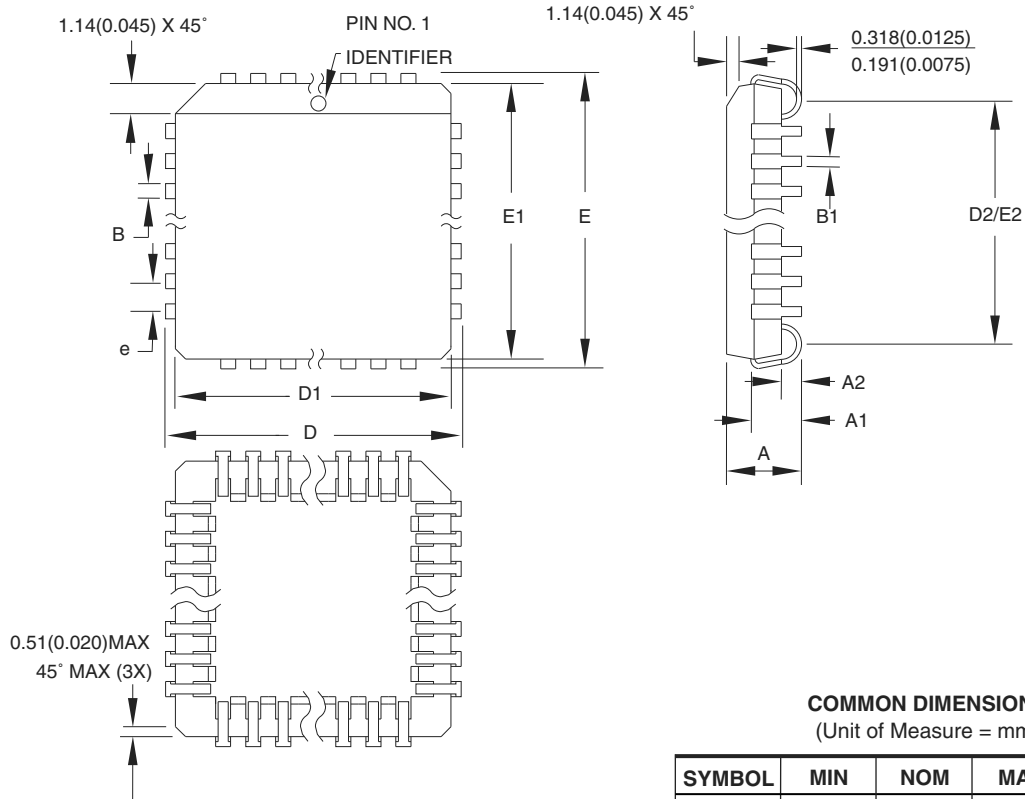
SYMBOL	MIN	NOM	MAX	NOTE
A	—	—	1.20	
A1	0.05	—	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
E	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
B	0.30	—	0.45	
C	0.09	—	0.20	
L	0.45	—	0.75	
e	0.80 TYP			

- Notes:
1. This package conforms to JEDEC reference MS-026, Variation ACB.
 2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
 3. Lead coplanarity is 0.10 mm maximum.

10/5/2001

2325 Orchard Parkway San Jose, CA 95131	TITLE 44A , 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	DRAWING NO. 44A	REV. B
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39.2 44J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

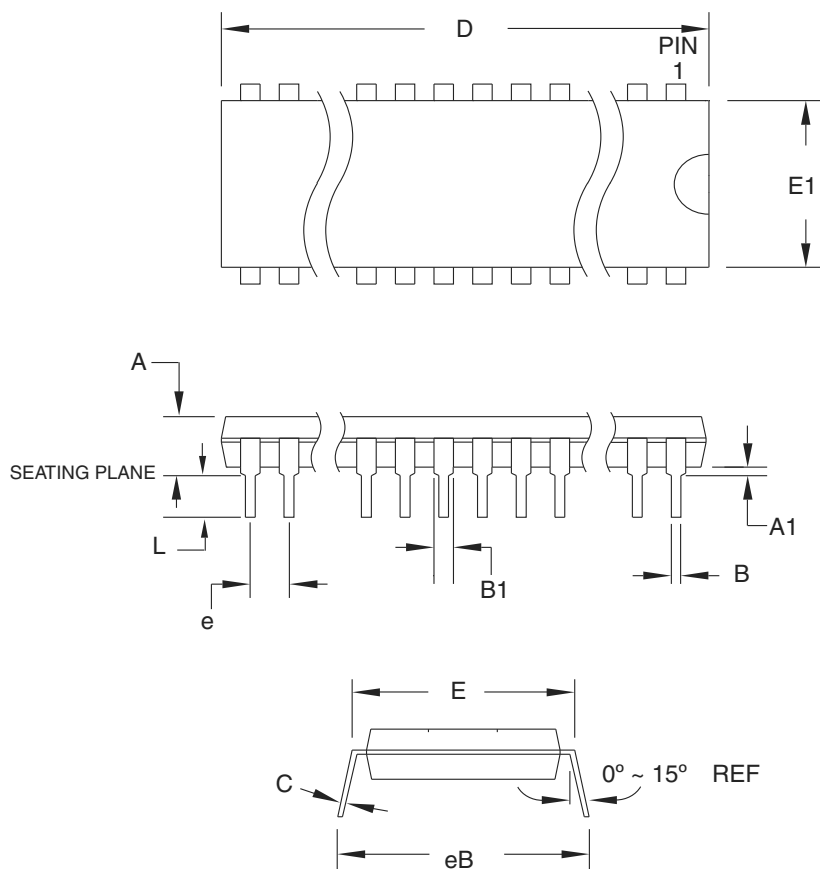
SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	—	4.572	
A1	2.286	—	3.048	
A2	0.508	—	—	
D	17.399	—	17.653	
D1	16.510	—	16.662	Note 2
E	17.399	—	17.653	
E1	16.510	—	16.662	Note 2
D2/E2	14.986	—	16.002	
B	0.660	—	0.813	
B1	0.330	—	0.533	
e	1.270 TYP			

- Notes:
1. This package conforms to JEDEC reference MS-018, Variation AC.
 2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010" (0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
 3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

2325 Orchard Parkway San Jose, CA 95131	TITLE 44J , 44-lead, Plastic J-leaded Chip Carrier (PLCC)	DRAWING NO. 44J	REV. B
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39.3 40P6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	—	—	4.826	
A1	0.381	—	—	
D	52.070	—	52.578	Note 2
E	15.240	—	15.875	
E1	13.462	—	13.970	Note 2
B	0.356	—	0.559	
B1	1.041	—	1.651	
L	3.048	—	3.556	
C	0.203	—	0.381	
eB	15.494	—	17.526	
e	2.540 TYP			

- Notes:
1. This package conforms to JEDEC reference MS-011, Variation AC.
 2. Dimensions D and E1 do not include mold Flash or Protrusion.
Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

09/28/01

2325 Orchard Parkway
San Jose, CA 95131

TITLE

40P6, 40-lead (0.600"/15.24 mm Wide) Plastic Dual
Inline Package (PDIP)

DRAWING NO.

40P6

REV.

B



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